

MOS INTEGRATED CIRCUIT

μ PD42S16160L, 4216160L, 42S18160L, 4218160L

3.3 V OPERATION 16M-BIT DYNAMIC RAM

1M-WORD BY 16-BIT, FAST PAGE MODE, BYTE READ/WRITE MODE

Description

The μ PD42S16160L, 4216160L, 42S18160L, 4218160L are 1 048 576 words by 16 bits dynamic CMOS RAMs. These differ in refresh cycle and the μ PD42S16160L, 42S18160L can execute $\overline{\text{CAS}}$ before $\overline{\text{RAS}}$ self refresh (see the table below).

These are packed in 50-pin plastic TSOP(II) and 42-pin plastic SOJ.

Features

- 1 048 576 words by 16 bits organization
- Single +3.3 V $\pm$ 0.3 V power supply
- Fast page mode
- Byte read/write mode
- Fast access and cycle time

Part number	Power consumption Active (MAX.)	Access time (MAX.)	R/W cycle time (MIN.)	Fast page mode cycle time (MIN.)
μ PD42S16160L-A60, 4216160L-A60	324 mW	60 ns	110 ns	40 ns
μ PD42S18160L-A60, 4218160L-A60	540 mW			
μ PD42S16160L-A70, 4216160L-A70	288 mW	70 ns	130 ns	45 ns
μ PD42S18160L-A70, 4218160L-A70	504 mW			

- The μ PD42S16160L, 42S18160L can execute $\overline{\text{CAS}}$ before $\overline{\text{RAS}}$ self refresh

Part number	Refresh cycle	Refresh	Power consumption at standby (MAX.)
μ PD42S16160L	4 096 cycles/128 ms	$\overline{\text{CAS}}$ before $\overline{\text{RAS}}$ self refresh, $\overline{\text{CAS}}$ before $\overline{\text{RAS}}$ refresh, $\overline{\text{RAS}}$ only refresh, hidden refresh	0.54 mW (CMOS level input)
μ PD42S18160L	1 024 cycles/128 ms		
μ PD4216160L	4 096 cycles/64 ms	$\overline{\text{CAS}}$ before $\overline{\text{RAS}}$ refresh, $\overline{\text{RAS}}$ only refresh, hidden refresh	1.8 mW (CMOS level input)
μ PD4218160L	1 024 cycles/16 ms		

The information in this document is subject to change without notice.

Ordering Information

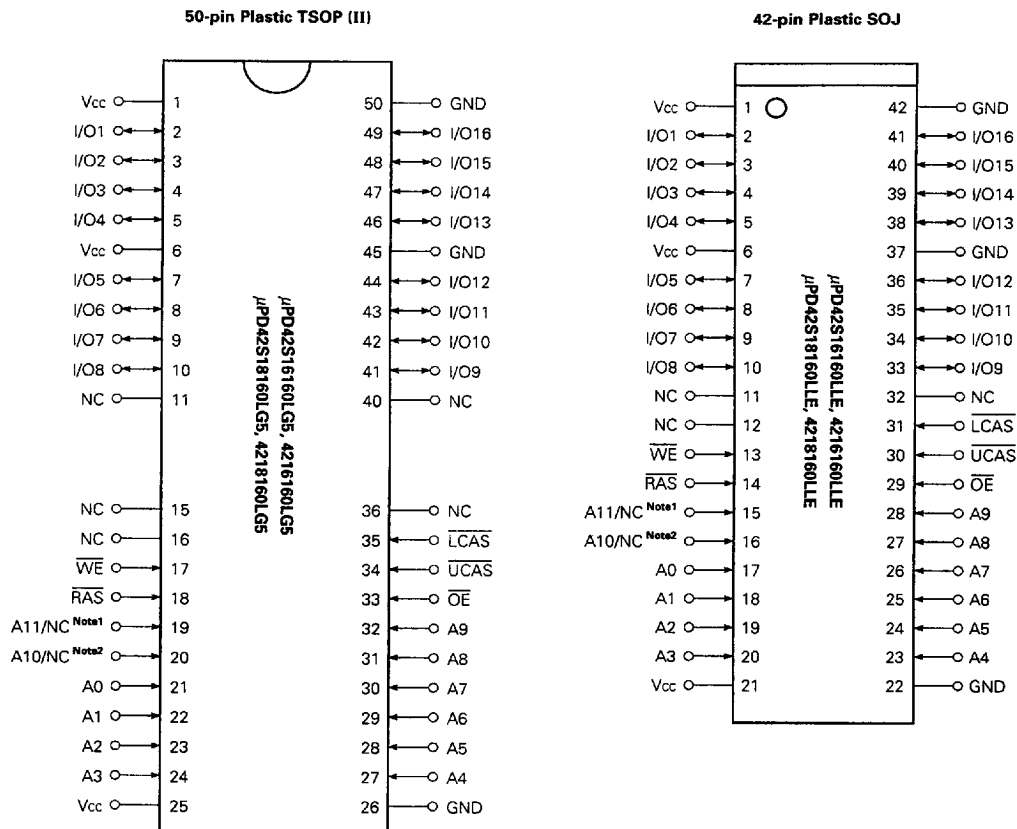
Part number	Access time (MAX.)	Package	Refresh
μPD42S16160LG5-A60	60 ns	50-pin Plastic TSOP (II) (400 mil)	$\overline{\text{CAS}}$ before $\overline{\text{RAS}}$ self refresh $\overline{\text{CAS}}$ before $\overline{\text{RAS}}$ refresh $\overline{\text{RAS}}$ only refresh Hidden refresh
μPD42S18160LG5-A60			
μPD42S16160LG5-A70	70 ns		
μPD42S18160LG5-A70			
μPD42S16160LLE-A60	60 ns	42-pin Plastic SOJ (400 mil)	
μPD42S18160LLE-A60			
μPD42S16160LLE-A70	70 ns		
μPD42S18160LLE-A70			
μPD4216160LG5-A60	60 ns	50-pin Plastic TSOP (II) (400 mil)	$\overline{\text{CAS}}$ before $\overline{\text{RAS}}$ refresh $\overline{\text{RAS}}$ only refresh Hidden refresh
μPD4218160LG5-A60			
μPD4216160LG5-A70	70 ns		
μPD4218160LG5-A70			
μPD4216160LLE-A60	60 ns	42-pin Plastic SOJ (400 mil)	
μPD4218160LLE-A60			
μPD4216160LLE-A70	70 ns		
μPD4218160LLE-A70			

Quality Grade

Standard

Please refer to "Quality grade on NEC Semiconductor Devices" (Document number IEI-1209) published by NEC Corporation to know the specification of quality grade on the devices and its recommended applications.

Pin Configurations (Marking Side)



Notes 1. A11 ... μ PD42S16160L, 4216160L

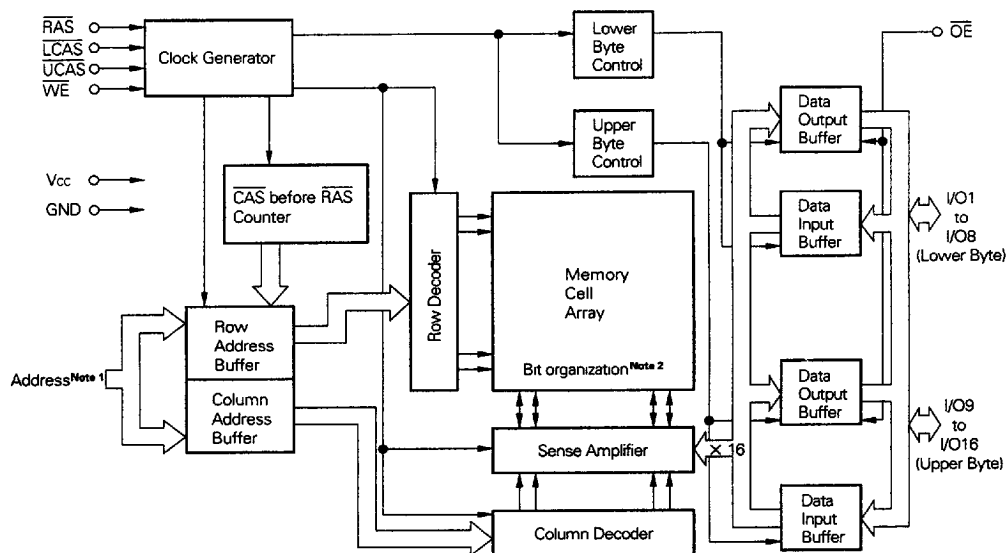
2. A10 ... μ PD42S16160L, 4216160L

NC ... μ PD42S18160L, 4218160L

NC ... μ PD42S18160L, 4218160L

A0 to A11 : Address Inputs
I/O1 to I/O16 : Data Inputs/Outputs
 $\overline{RAS}$: Row Address Strobe
 $\overline{UCAS}$: Column Address Strobe (upper)
 $\overline{LCAS}$: Column Address Strobe (lower)
 $\overline{WE}$: Write Enable
 $\overline{OE}$: Output Enable
Vcc : Power Supply
GND : Ground
NC : No Connection

Block Diagram



Notes 1.

Part number	Row address	Column address
μPD42S16160L, 4216160L	A0 to A11	A0 to A7
μPD42S18160L, 4218160L	A0 to A9	A0 to A9

2. μPD42S16160L, 4216160L ... 4 096 × 256 × 16 μPD42S18160L, 4218160L ... 1 024 × 1 024 × 16

Input/Output Pin Functions

The μPD42S16160L, 4216160L, 42S18160L, 4218160L have input pins $\overline{\text{RAS}}$, $\overline{\text{CAS}}$ ^{Note1}, $\overline{\text{WE}}$, $\overline{\text{OE}}$, A0 to A11/A9 ^{Note2} and input/output pins I/O1 to I/O16.

Pin name	Input/ Output	Function
$\overline{\text{RAS}}$ (Row address strobe)	Input	$\overline{\text{RAS}}$ activates the sense amplifier by latching a row address and selecting a corresponding word line. It refreshes memory cell array of one line selected by the row address. It also selects the following function. • $\overline{\text{CAS}}$ before $\overline{\text{RAS}}$ refresh
$\overline{\text{CAS}}$ (Column address strobe)		$\overline{\text{CAS}}$ activates data input/output circuit by latching column address and selecting a digit line connected with the sense amplifier.
A0 to A11/A9 ^{Note2} (Address inputs)		Address bus. Input total 20-bit of address signal, upper 12/10 ^{Note3} -bit and lower 8/10 ^{Note4} -bit in sequence (address multiplex method). Therefore, one word is selected from 1 048 576-word by 16-bit memory cell array. In actual operation, latch row address by specifying row address and activating $\overline{\text{RAS}}$. Then, switch the address bus to column address and activate $\overline{\text{CAS}}$. Each address is taken into the device when $\overline{\text{RAS}}$ and $\overline{\text{CAS}}$ are activated. Therefore, the address input setup time (t_{ASR} , t_{ASC}) and hold time (t_{RAH} , t_{CAH}) are specified for the activation of $\overline{\text{RAS}}$ and $\overline{\text{CAS}}$.
$\overline{\text{WE}}$ (Write enable)		Write control signal. Write operation is executed by activating $\overline{\text{RAS}}$, $\overline{\text{CAS}}$ and $\overline{\text{WE}}$.
$\overline{\text{OE}}$ (Output enable)	Input/ Output	Read control signal. Read operation can be executed by activating $\overline{\text{RAS}}$, $\overline{\text{CAS}}$ and $\overline{\text{OE}}$. If $\overline{\text{WE}}$ is activated during read operation, $\overline{\text{OE}}$ is to be ineffective in the device. Therefore, read operation cannot be executed.
I/O1 to I/O16 (Data inputs/outputs)		16-bit data bus. I/O1 to I/O16 are used to input/output data.

- Notes**
1. $\overline{\text{CAS}}$ means $\overline{\text{UCAS}}$ and $\overline{\text{LCAS}}$.
 2. A11 ... μPD42S16160L, 4216160L A9 ... μPD42S18160L, 4218160L
 3. 12 ... μPD42S16160L, 4216160L 10 ... μPD42S18160L, 4218160L
 4. 8 ... μPD42S16160L, 4216160L 10 ... μPD42S18160L, 4218160L

Electrical Specifications

- CAS means $\overline{\text{UCAS}}$ and $\overline{\text{LCAS}}$.
- All voltages are referenced to GND.
- After power up, wait more than 100 μs and then, execute eight $\overline{\text{CAS}}$ before $\overline{\text{RAS}}$ or $\overline{\text{RAS}}$ only refresh cycles as dummy cycles to initialize internal circuit.

Absolute Maximum Ratings

Parameter	Symbol	Condition	Rating	Unit
Voltage on any pin relative to GND	V_T		- 0.5 to +4.6	V
Supply voltage	V_{CC}		- 0.5 to +4.6	V
Output current	I_O		20	mA
Power dissipation	P_D		1	W
Operating temperature	T_{opt}		0 to +70	°C
Storage temperature	T_{stg}		- 55 to +125	°C

Caution Exposing the device to stress above those listed in Absolute Maximum Ratings could cause permanent damage. The device is not meant to be operated under conditions outside the limits described in the operational section of this specification. Exposure to Absolute Maximum Rating conditions for extended periods may affect device reliability.

Recommended Operating Conditions

Parameter	Symbol	Condition	MIN.	TYP.	MAX.	Unit
Supply voltage	V_{CC}		3.0	3.3	3.6	V
High level input voltage	V_{IH}		2.0		$V_{CC} + 0.3$	V
Low level input voltage	V_{IL}		- 0.3		+0.8	V
Ambient temperature	T_A		0		70	°C

Capacitance ($T_A = +25\text{ }^{\circ}\text{C}$, $f = 1\text{ MHz}$)

Parameter	Symbol	Test condition	MIN.	TYP.	MAX.	Unit
Input capacitance	C_{I1}	A0 to A11			5	pF
	C_{I2}	$\overline{\text{RAS}}$, $\overline{\text{CAS}}$, $\overline{\text{WE}}$, $\overline{\text{OE}}$			7	pF
Data Input/Output capacitance	$C_{I/O}$	I/O1 to I/O16			7	pF

DC Characteristics (Recommended Operating Conditions unless otherwise noted)

[μPD42S16160L, 4216160L]

Parameter	Symbol	Test condition	MIN.	MAX.	Unit	Notes
Operating current	I _{CC1}	RAS, CAS Cycling t _{RC} = t _{RC} (MIN.) I _O = 0 mA	t _{RAC} = 60 ns	90	mA	1,2,3
			t _{RAC} = 70 ns	80		
Standby current	μPD42S16160L	RAS, CAS ≥ V _{IH} (MIN.) I _O = 0 mA		0.5	mA	
		RAS, CAS ≥ V _{CC} - 0.2 V I _O = 0 mA		0.15		
	μPD4216160L	RAS, CAS ≥ V _{IH} (MIN.) I _O = 0 mA		2		
		RAS, CAS ≥ V _{CC} - 0.2 V I _O = 0 mA		0.5		
RAS only refresh current	I _{CC3}	RAS Cycling CAS ≥ V _{IH} (MIN.) t _{RC} = t _{RC} (MIN.) I _O = 0 mA	t _{RAC} = 60 ns	90	mA	1,2,3,4
			t _{RAC} = 70 ns	80		
Operating current (Fast page mode)	I _{CC4}	RAS ≤ V _{IL} (MAX.) CAS Cycling t _{PC} = t _{PC} (MIN.) I _O = 0 mA	t _{RAC} = 60 ns	90	mA	1,2,5
			t _{RAC} = 70 ns	80		
CAS before RAS refresh current	I _{CC5}	RAS Cycling t _{RC} = t _{RC} (MIN.) I _O = 0 mA	t _{RAC} = 60 ns	90	mA	1,2
			t _{RAC} = 70 ns	80		
CAS before RAS long refresh current (4 096 cycles / 128 ms, only for μPD42S16160L)	I _{CC6}	CAS before RAS refresh : 4 096 cycles/128 ms RAS, CAS : V _{CC} -0.2 V ≤ V _{IH} ≤ V _{IH} (MAX.) 0 V ≤ V _{IL} ≤ 0.2 V Standby : RAS ≥ V _{CC} -0.2 V Address : Don't care WE, OE : V _{IH} I _O = 0 mA	t _{RAS} ≤ 1 μs	220	μA	1,2
Self refresh current (CAS before RAS self refresh, only for μPD42S16160L)	I _{CC7}	RAS, CAS : V _{CC} -0.2 V ≤ V _{IH} ≤ V _{IH} (MAX.) 0 V ≤ V _{IL} ≤ 0.2 V I _O = 0 mA		150	μA	2
Input leakage current	I _I (L)	V _I = 0 to 3.6 V all other pins not under test = 0 V	-5	+5	μA	
Output leakage current	I _O (L)	Output is disabled (Hi-Z) V _O = 0 to 3.6 V	-5	+5	μA	
High level output voltage	V _{OH}	I _O = -2.0 mA	2.4		V	
Low level output voltage	V _{OL}	I _O = 2.0 mA		0.4	V	

[μ PD42S18160L, 4218160L]

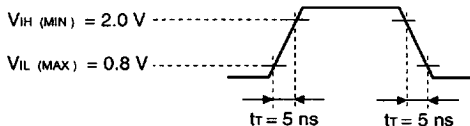
Parameter		Symbol	Test condition	MIN.	MAX.	Unit	Notes
Operating current		I _{CC1}	RAS, CAS Cycling trc = trc(MIN.) I _O = 0 mA	trAC = 60 ns	150	mA	1,2,3
				trAC = 70 ns	140		
Standby current	μ PD42S18160L	I _{CC2}	RAS, CAS $\geq V_{IH(MIN.)}$	I _O = 0 mA	0.5	mA	
			RAS, CAS $\geq V_{CC} - 0.2$ V	I _O = 0 mA	0.15		
	μ PD4218160L		RAS, CAS $\geq V_{IH(MIN.)}$	I _O = 0 mA	2		
			RAS, CAS $\geq V_{CC} - 0.2$ V	I _O = 0 mA	0.5		
RAS only refresh current		I _{CC3}	RAS Cycling CAS $\geq V_{IH(MIN.)}$ trc = trc(MIN.) I _O = 0 mA	trAC = 60 ns	150	mA	1,2,3,4
				trAC = 70 ns	140		
Operating current (Fast page mode)		I _{CC4}	RAS $\leq V_{IL(MAX.)}$ CAS Cycling tpc = tpc(MIN.) I _O = 0 mA	trAC = 60 ns	90	mA	1,2,5
				trAC = 70 ns	80		
CAS before RAS refresh current		I _{CC5}	RAS Cycling trc = trc(MIN.) I _O = 0 mA	trAC = 60 ns	150	mA	1,2
				trAC = 70 ns	140		
CAS before RAS long refresh current (1 024 cycles / 128 ms, only for μ PD42S18160L)		I _{CC6}	CAS before RAS refresh : 1 024 cycles/128 ms RAS, CAS : $V_{CC}-0.2$ V $\leq V_{IH} \leq V_{IH(MAX.)}$ 0 V $\leq V_{IL} \leq 0.2$ V Standby : RAS $\geq V_{CC}-0.2$ V Address : Don't care WE, OE : V _{IH} I _O = 0 mA	trAS ≤ 1 μ s	180	μ A	1,2
Self refresh current (CAS before RAS self refresh, only for μ PD42S18160L)		I _{CC7}	RAS, CAS : $V_{CC}-0.2$ V $\leq V_{IH} \leq V_{IH(MAX.)}$ 0 V $\leq V_{IL} \leq 0.2$ V I _O = 0 mA		150	μ A	2
Input leakage current		I _{I(L)}	V _I = 0 to 3.6 V all other pins not under test = 0 V	-5	+5	μ A	
Output leakage current		I _{O(L)}	Output is disabled (Hi-Z) V _O = 0 to 3.6 V	-5	+5	μ A	
High level output voltage		V _{OH}	I _O = -2.0 mA	2.4		V	
Low level output voltage		V _{OL}	I _O = 2.0 mA		0.4	V	

- Notes**
1. I_{CC1}, I_{CC3}, I_{CC4}, I_{CC5} and I_{CC6} depend on cycle rates (trc and tpc).
 2. Specified values are obtained with outputs unloaded.
 3. I_{CC1} and I_{CC3} are measured assuming that address can be changed once or less during RAS $\leq V_{IL(MAX.)}$ and CAS $\geq V_{IH(MIN.)}$.
 4. I_{CC3} is measured assuming that all column address inputs are held at either high or low.
 5. I_{CC4} is measured assuming that all column address inputs are switched only once during each fast page cycle.

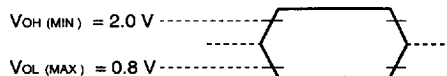
AC Characteristics (Recommended Operating Conditions unless otherwise noted)

AC Characteristics Test Conditions

(1) Input timing specification



(2) Output timing specification



(3) Loading conditions are 100 pF + 1 TTL.

Common to Read, Write, Read Modify Write Cycle

Parameter		Symbol	t _{RAC} = 60 ns		t _{RAC} = 70 ns		Unit	Notes
			MIN.	MAX.	MIN.	MAX.		
Read / Write Cycle Time		t _{RC}	110	–	130	–	ns	
RAS Precharge Time		t _{RP}	40	–	50	–	ns	
CAS Precharge Time		t _{CPN}	10	–	10	–	ns	
RAS Pulse Width		t _{RAS}	60	10 000	70	10 000	ns	
CAS Pulse Width		t _{CAS}	15	10 000	20	10 000	ns	
RAS Hold Time		t _{RSH}	15	–	18	–	ns	
CAS Hold Time		t _{CSH}	60	–	70	–	ns	
RAS to CAS Delay Time		t _{RCD}	20	45	20	50	ns	1
RAS to Column Address Delay Time		t _{RAD}	15	30	15	35	ns	1
CAS to RAS Precharge Time		t _{CRP}	5	–	5	–	ns	2
Row Address Setup Time		t _{ASR}	0	–	0	–	ns	
Row Address Hold Time		t _{RAH}	10	–	10	–	ns	
Column Address Setup Time		t _{ASC}	0	–	0	–	ns	
Column Address Hold Time		t _{CAH}	15	–	15	–	ns	
OE Lead Time Referenced to RAS		t _{OES}	0	–	0	–	ns	
CAS to Data Setup Time		t _{CLZ}	0	–	0	–	ns	
OE to Data Setup Time		t _{OLZ}	0	–	0	–	ns	
OE to Data Delay Time		t _{OED}	13	–	15	–	ns	
Masked Byte Write Hold Time Referenced to RAS		t _{MRH}	0	–	0	–	ns	
Transition Time (Rise and Fall)		t _T	3	50	3	50	ns	
Refresh Time	μPD42S16160L, 42S18160L	t _{REF}	–	128	–	128	ms	3
	μPD4216160L		–	64	–	64		
	μPD4218160L		–	16	–	16		

Notes 1. For read cycles, access time is defined as follows:

Input Conditions	Access Time	Access Time from $\overline{\text{RAS}}$
$\text{trAD} \leq \text{trAD (MAX.)}$ and $\text{trCD} \leq \text{trCD (MAX.)}$	trAC (MAX.)	trAC (MAX.)
$\text{trAD} > \text{trAD (MAX.)}$ and $\text{trCD} \leq \text{trCD (MAX.)}$	tAA (MAX.)	$\text{trAD} + \text{tAA (MAX.)}$
$\text{trCD} > \text{trCD (MAX.)}$	tCAC (MAX.)	$\text{trCD} + \text{tCAC (MAX.)}$

trAD(MAX.) and trCD(MAX.) are specified as reference points only ; they are not restrictive operating parameters. They are used to determine which access time (trAC , tAA or tCAC) is to be used for finding out when output data will be available. Therefore, the input conditions $\text{trAD} \geq \text{trAD(MAX.)}$ and $\text{trCD} \geq \text{trCD(MAX.)}$ will not cause any operation problems.

- tCRP(MIN.) requirement is applied to $\overline{\text{RAS}}$, $\overline{\text{CAS}}$ cycles.
- This specification is applied only to the μ PD42S16160L, 42S18160L.

Read Cycle

Parameter	Symbol	$\text{trAC} = 60 \text{ ns}$		$\text{trAC} = 70 \text{ ns}$		Unit	Notes
		MIN.	MAX.	MIN.	MAX.		
Access Time from $\overline{\text{RAS}}$	trAC	–	60	–	70	ns	1
Access Time from $\overline{\text{CAS}}$	tCAC	–	15	–	20	ns	1
Access Time from Column Address	tAA	–	30	–	35	ns	1
Access Time from $\overline{\text{OE}}$	tOEA	–	15	–	20	ns	
Column Address Lead Time Referenced to $\overline{\text{RAS}}$	trAL	30	–	35	–	ns	
Read Command Setup Time	trCS	0	–	0	–	ns	
Read Command Hold Time Referenced to $\overline{\text{RAS}}$	trRH	0	–	0	–	ns	2
Read Command Hold Time Referenced to $\overline{\text{CAS}}$	trCH	0	–	0	–	ns	2
Output Buffer Turn-off Delay Time from $\overline{\text{OE}}$	tOEZ	0	13	0	15	ns	3
Output Buffer Turn-off Delay Time from $\overline{\text{CAS}}$	tOFF	0	13	0	15	ns	3

Notes 1. For read cycles, access time is defined as follows:

Input Conditions	Access Time	Access Time from $\overline{\text{RAS}}$
$\text{trAD} \leq \text{trAD (MAX.)}$ and $\text{trCD} \leq \text{trCD (MAX.)}$	trAC (MAX.)	trAC (MAX.)
$\text{trAD} > \text{trAD (MAX.)}$ and $\text{trCD} \leq \text{trCD (MAX.)}$	tAA (MAX.)	$\text{trAD} + \text{tAA (MAX.)}$
$\text{trCD} > \text{trCD (MAX.)}$	tCAC (MAX.)	$\text{trCD} + \text{tCAC (MAX.)}$

trAD(MAX.) and trCD(MAX.) are specified as reference points only ; they are not restrictive operating parameters. They are used to determine which access time (trAC , tAA or tCAC) is to be used for finding out when output data will be available. Therefore, the input conditions $\text{trAD} \geq \text{trAD(MAX.)}$ and $\text{trCD} \geq \text{trCD(MAX.)}$ will not cause any operation problems.

- Either trCH(MIN.) or trRH(MIN.) should be met in read cycles.
- tOFF(MAX.) and tOEZ(MAX.) define the time when the output achieves the condition of Hi-Z and is not referenced to V_{OH} or V_{OL} .

Write Cycle

Parameter	Symbol	t _{RAC} = 60 ns		t _{RAC} = 70 ns		Unit	Notes
		MIN.	MAX.	MIN.	MAX.		
$\overline{WE}$ Hold Time Referenced to $\overline{CAS}$	twch	10	–	10	–	ns	1
$\overline{WE}$ Pulse Width	twp	10	–	10	–	ns	1
$\overline{WE}$ Lead Time Referenced to $\overline{RAS}$	trwl	20	–	20	–	ns	
$\overline{WE}$ Lead Time Referenced to $\overline{CAS}$	tcwl	15	–	15	–	ns	
$\overline{WE}$ Setup Time	twcs	0	–	0	–	ns	2
$\overline{OE}$ Hold Time	toeh	0	–	0	–	ns	
Data-in Setup Time	t _{ds}	0	–	0	–	ns	3
Data-in Hold Time	t _{dh}	10	–	15	–	ns	3

- Notes**
1. t_{wp(MIN.)} is applied to late write cycles or read modify write cycles. In early write cycles, t_{wch(MIN.)} should be met.
 2. If t_{wcs} $\geq$ t_{wcs(MIN.)}, the cycle is an early write cycle and the data out will remain Hi-Z through the entire cycle.
 3. t_{ds(MIN.)} and t_{dh(MIN.)} are referenced to the $\overline{CAS}$ falling edge in early write cycles. In late write cycles and read modify write cycles, they are referenced to the $\overline{WE}$ falling edge.

Read Modify Write Cycle

Parameter	Symbol	t _{RAC} = 60 ns		t _{RAC} = 70 ns		Unit	Note
		MIN.	MAX.	MIN.	MAX.		
Read Modify Write Cycle Time	trwc	160	–	180	–	ns	
$\overline{RAS}$ to $\overline{WE}$ Delay Time	trwd	83	–	95	–	ns	1
$\overline{CAS}$ to $\overline{WE}$ Delay Time	tcwd	38	–	40	–	ns	1
Column Address to $\overline{WE}$ Delay Time	tawd	53	–	60	–	ns	1

- Note**
1. If t_{wcs} $\geq$ t_{wcs(MIN.)}, the cycle is an early write cycle and the data out will remain Hi-Z through the entire cycle. If t_{trwd} $\geq$ t_{trwd(MIN.)}, t_{tcwd} $\geq$ t_{tcwd(MIN.)}, t_{tawd} $\geq$ t_{tawd(MIN.)} and t_{tcpwd} $\geq$ t_{tcpwd(MIN.)}, the cycle is a read modify write cycle and the data out will contain data read from the selected cell. If neither of the above conditions is met, the state of the data out is indeterminate.

Fast Page Mode

Parameter	Symbol	t _{RAC} = 60 ns		t _{RAC} = 70 ns		Unit	Note
		MIN.	MAX.	MIN.	MAX.		
Fast Page Mode Cycle Time	t _{PC}	40	–	45	–	ns	
Access Time from $\overline{\text{CAS}}$ Precharge	t _{ACP}	–	35	–	40	ns	
$\overline{\text{RAS}}$ Pulse Width	t _{RASP}	60	125 000	70	125 000	ns	
$\overline{\text{CAS}}$ Precharge Time	t _{CP}	10	–	10	–	ns	
$\overline{\text{RAS}}$ Hold Time from $\overline{\text{CAS}}$ Precharge	t _{RHCP}	35	–	40	–	ns	
Read Modify Write Cycle Time	t _{PRWC}	85	–	90	–	ns	
$\overline{\text{CAS}}$ Precharge to $\overline{\text{WE}}$ Delay Time	t _{CPWD}	60	–	65	–	ns	1

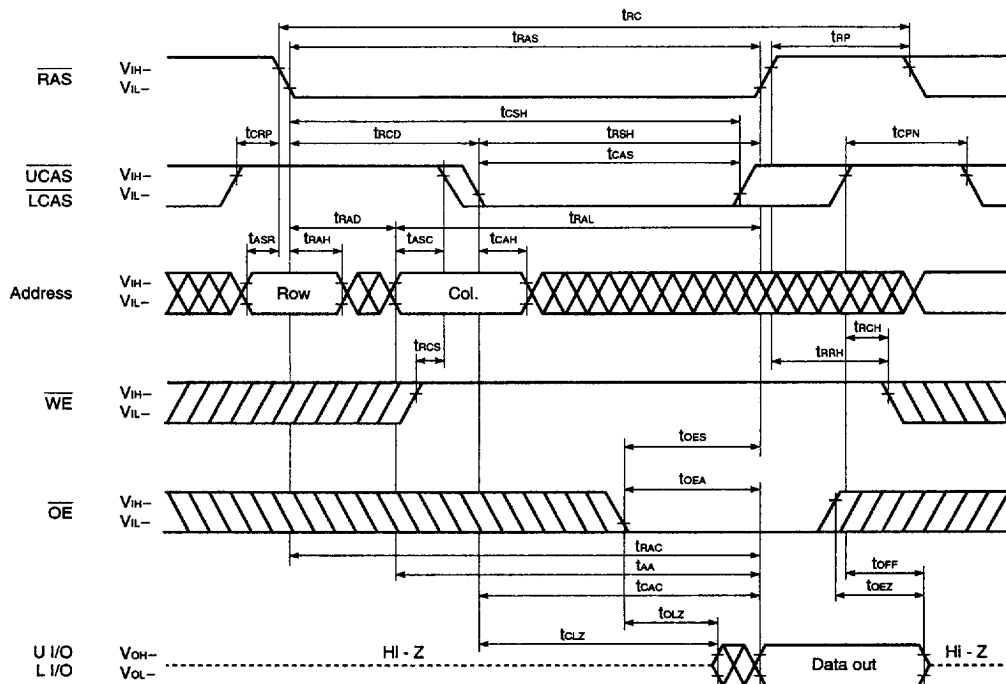
Note 1. If $\text{twcs} \geq \text{twcs}(\text{MIN.})$, the cycle is an early write cycle and the data out will remain Hi - Z through the entire cycle. If $\text{trwd} \geq \text{trwd}(\text{MIN.})$, $\text{tcwd} \geq \text{tcwd}(\text{MIN.})$, $\text{tawd} \geq \text{tawd}(\text{MIN.})$ and $\text{tcpwd} \geq \text{tcpwd}(\text{MIN.})$, the cycle is a read modify write cycle and the data out will contain data read from the selected cell. If neither of the above conditions is met, the state of the data out is indeterminate.

Refresh Cycle

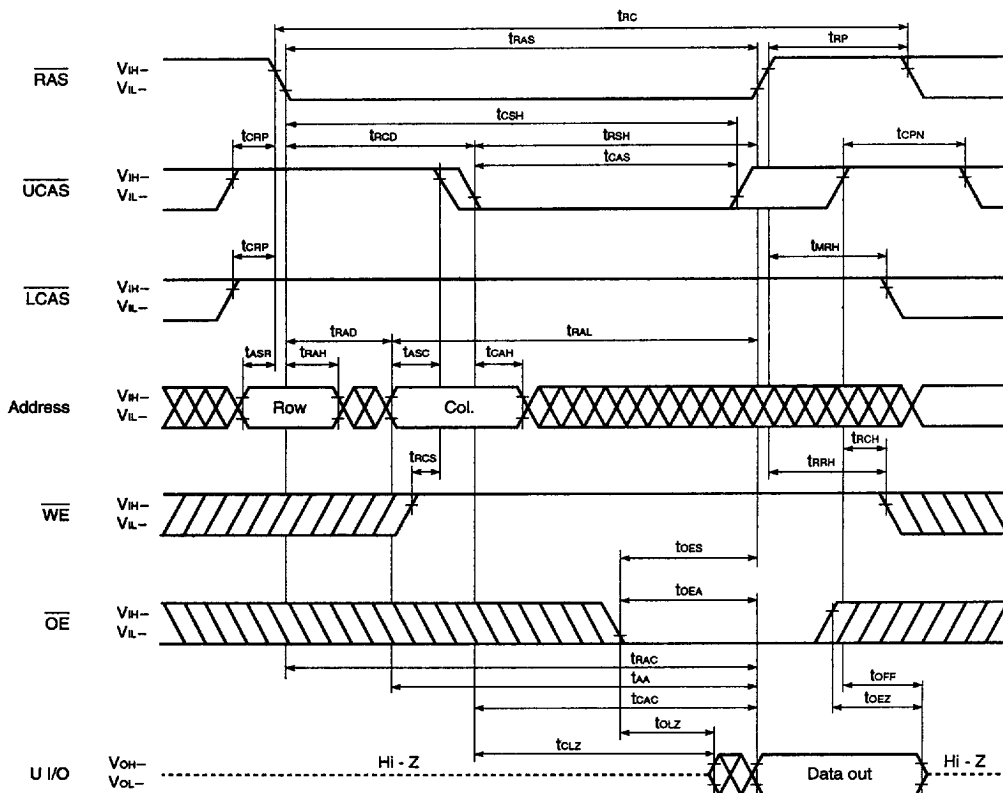
Parameter	Symbol	t _{RAC} = 60 ns		t _{RAC} = 70 ns		Unit	Note
		MIN.	MAX.	MIN.	MAX.		
$\overline{\text{CAS}}$ Setup Time	t _{CSR}	5	–	5	–	ns	
$\overline{\text{CAS}}$ Hold Time ($\overline{\text{CAS}}$ before $\overline{\text{RAS}}$ Refresh)	t _{CHR}	10	–	10	–	ns	
$\overline{\text{RAS}}$ Precharge $\overline{\text{CAS}}$ Hold Time	t _{RPC}	5	–	5	–	ns	
$\overline{\text{RAS}}$ Pulse Width ($\overline{\text{CAS}}$ before $\overline{\text{RAS}}$ Self Refresh Cycle)	t _{RASS}	100	–	100	–	μ s	1
$\overline{\text{RAS}}$ Precharge Time ($\overline{\text{CAS}}$ before $\overline{\text{RAS}}$ Self Refresh Cycle)	t _{RPS}	110	–	130	–	ns	1
$\overline{\text{CAS}}$ Hold Time ($\overline{\text{CAS}}$ before $\overline{\text{RAS}}$ Self Refresh Cycle)	t _{CHS}	–50	–	–50	–	ns	1
$\overline{\text{WE}}$ Hold Time (Hidden Refresh Cycle)	t _{WHR}	15	–	15	–	ns	

Note 1. This specification is applied only to the μ PD42S16160L, 42S18160L.

Read Cycle

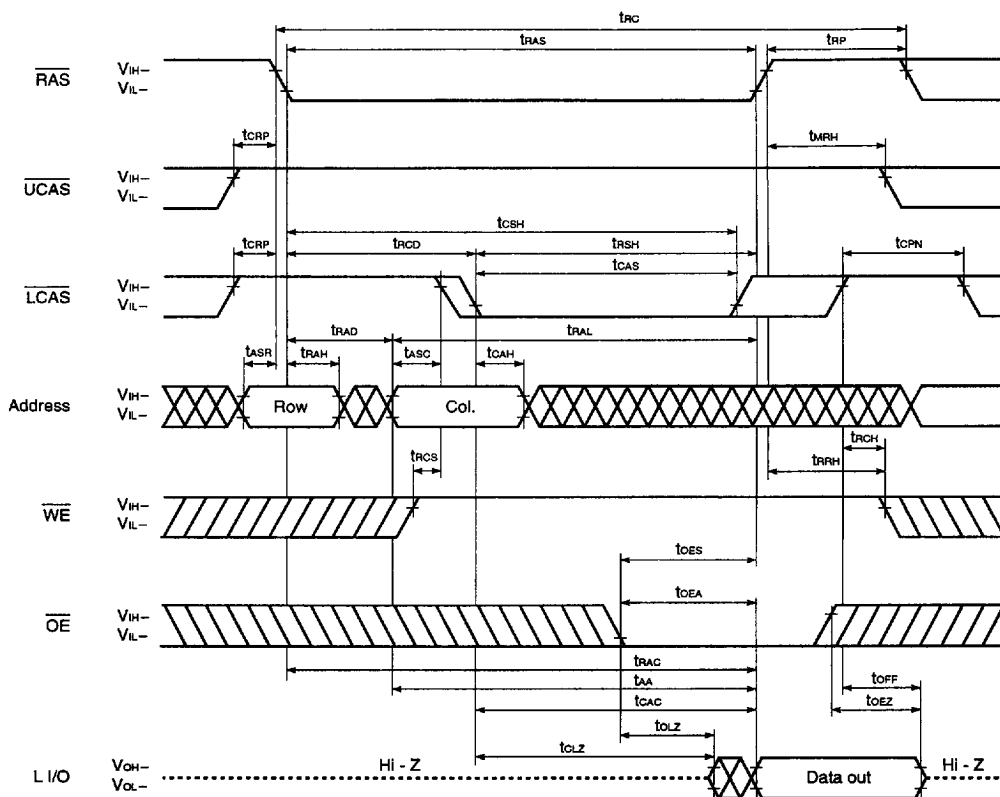


Upper Byte Read Cycle



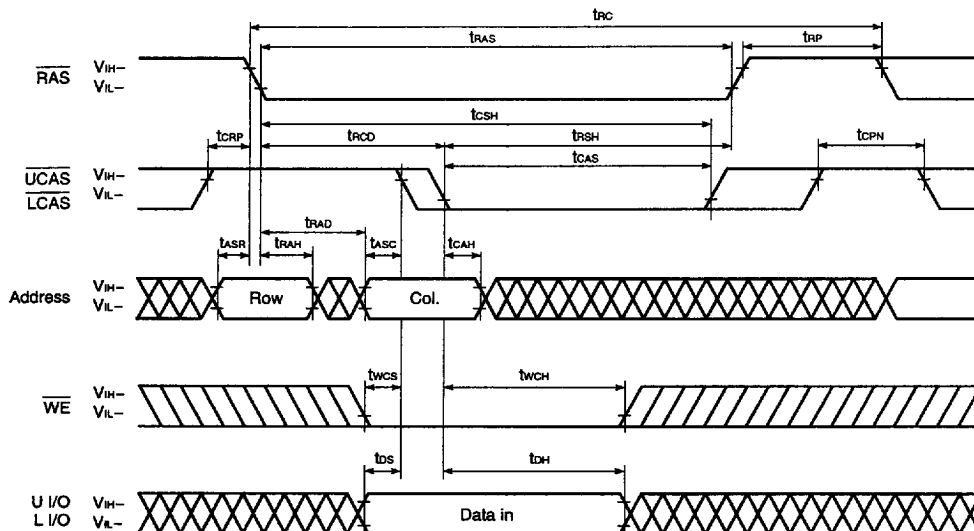
Remark L I/O : Hi-Z

Lower Byte Read Cycle



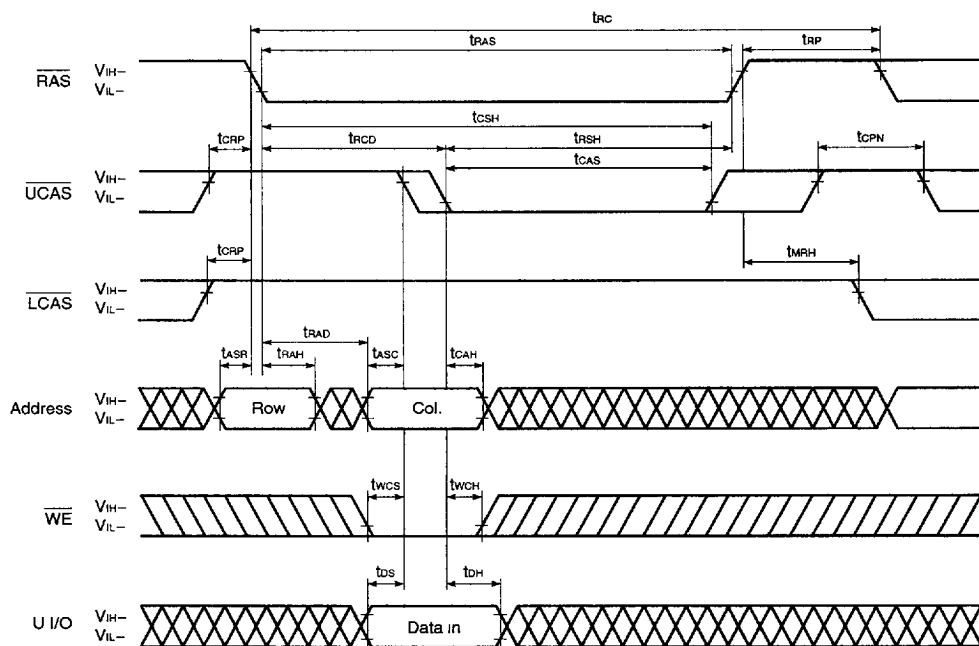
Remark U I/O : Hi-Z

Early Write Cycle



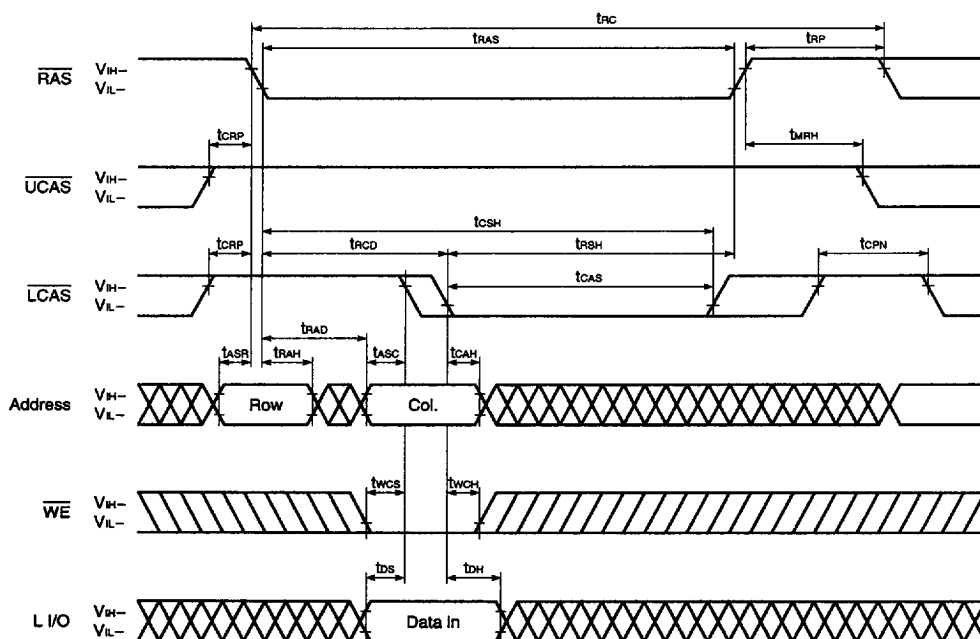
Remark $\overline{\text{OE}}$: Don't care

Upper Byte Early Write Cycle



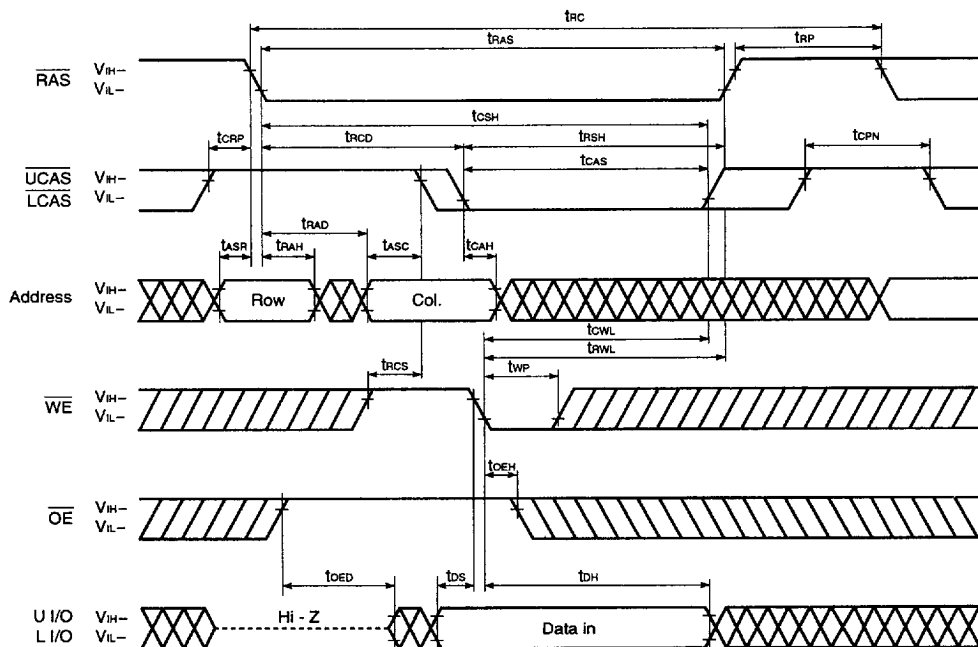
Remark $\overline{OE}$, L I/O : Don't care

Lower Byte Early Write Cycle

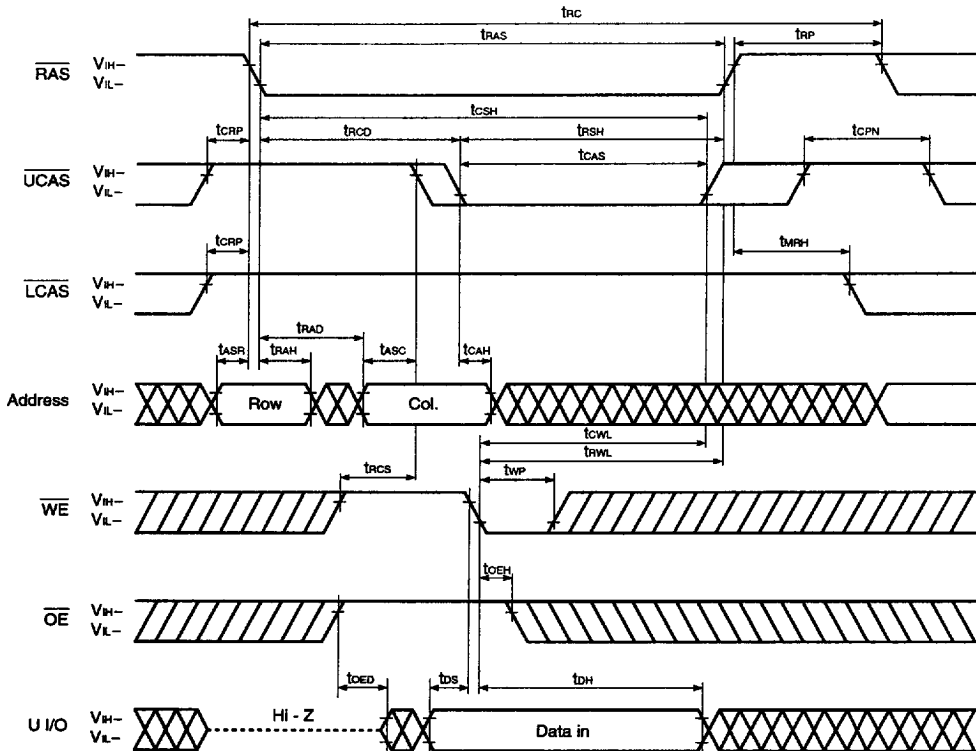


Remark $\overline{\text{OE}}$, U I/O : Don't care

Late Write Cycle

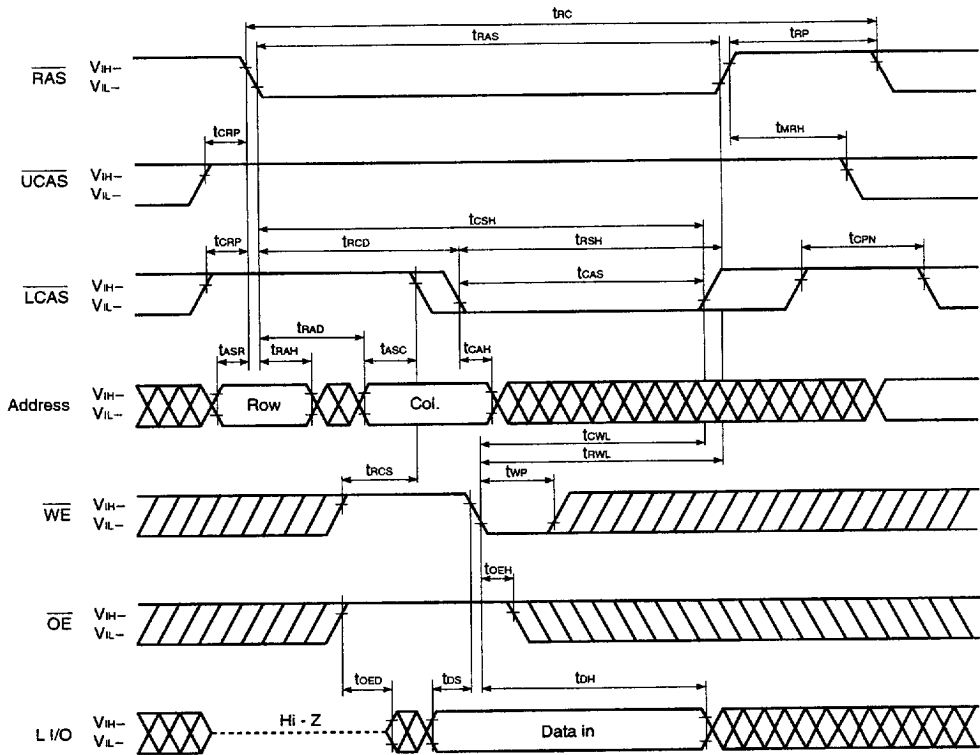


Upper Byte Late Write Cycle



Remark L I/O : Don't care

Lower Byte Late Write Cycle



Remark U I/O : Don't care

The diagram illustrates the timing relationships for the 64K1602 LCD controller. It shows the following signals and their timing parameters:

- RAS:** Row Address Strobe. Timing parameters: t_{RAS} (pulse width), t_{RP} (pulse period), t_{CRP} (setup time before RAS), t_{CSh} (setup time before RAS), t_{RSH} (hold time after RAS), t_{CPN} (pulse period).
- UCAS/LCAS:** Column Address Strobe/Latch Enable. Timing parameters: t_{RCD} (setup time before UCAS/LCAS), t_{CAS} (pulse width), t_{CPN} (pulse period).
- Address:** Row and Column Address. Timing parameters: t_{RAD} (Row Address delay), t_{ASR} (Row Address setup), t_{RAH} (Row Address hold), t_{ASC} (Column Address setup), t_{CAH} (Column Address hold), t_{RCS} (Row Address setup), t_{RWD} (Row Address delay), t_{LWD} (Row Address delay), t_{CWL} (Column Address delay), t_{RWL} (Column Address delay), t_{WP} (Write Pulse).
- WE:** Write Enable. Timing parameters: t_{OEa} (Output Enable delay), t_{OEh} (Output Enable hold).
- OE:** Output Enable. Timing parameters: t_{RAC} (Row Address delay), t_{AA} (Row Address delay), t_{CAC} (Column Address delay), t_{OED} (Output Enable delay), t_{DS} (Data Setup), t_{DH} (Data Hold).
- U I/O / L I/O:** Data Input/Output. Timing parameters: t_{OLZ} (Output Low-Z delay), t_{CLZ} (Output Low-Z delay), t_{OEZ} (Output Enable delay), t_{OH-Z} (Output High-Z delay), t_{OL-Z} (Output Low-Z delay).

[illegible]

Remark In this cycle, the input data to Lower I/O is ineffective. The data out of that remains Hi-Z.

The timing diagram illustrates the relationship between the 64K1602 LCD module and the microcontroller. The signals and their timing parameters are as follows:

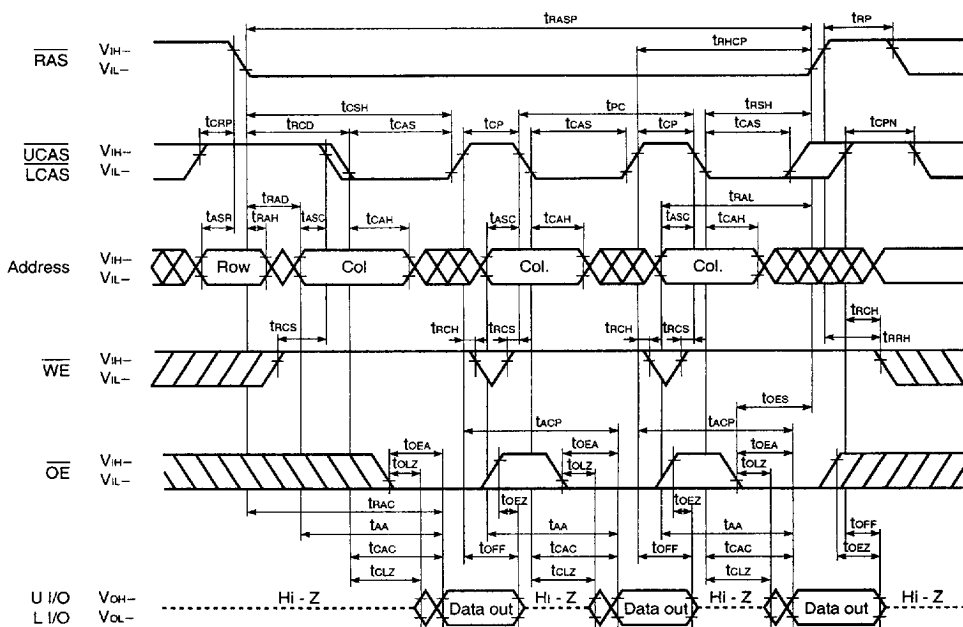
- RAS**: Row Address Strobe. Timing parameters: t_{RAS} (pulse width), t_{RWC} (time from RAS to WE), t_{RP} (time from RAS to next RAS), t_{CRP} (time from RAS to UCAS/LCAS).
- UCAS**: User Command Address Strobe. Timing parameters: t_{CRP} (time from UCAS to RAS), t_{MRH} (time from UCAS to next RAS).
- LCAS**: Local Command Address Strobe. Timing parameters: t_{CRP} (time from LCAS to RAS), t_{RCD} (time from LCAS to RAS), t_{CSh} (time from LCAS to RAS), t_{RSH} (time from LCAS to RAS), t_{CAS} (time from LCAS to RAS), t_{CPN} (time from LCAS to next RAS).
- Address**: Data bus for Row and Column addresses. Timing parameters: t_{ASR} (time from Address to RAS), t_{RAH} (time from Address to RAS), t_{ASC} (time from Address to RAS), t_{CAH} (time from Address to RAS).
- WE**: Write Enable. Timing parameters: t_{RWD} (time from WE to RAS), t_{AWD} (time from WE to RAS), t_{CWD} (time from WE to RAS), t_{CWL} (time from WE to RAS), t_{RWL} (time from WE to RAS), t_{WP} (time from WE to RAS).
- OE**: Output Enable. Timing parameters: t_{OEa} (time from OE to RAS), t_{OEh} (time from OE to RAS), t_{RAC} (time from OE to RAS), t_{AA} (time from OE to RAS), t_{CAC} (time from OE to RAS).
- L I/O**: Data bus for Local I/O. Timing parameters: t_{OEd} (time from OE to RAS), t_{DS} (time from OE to RAS), t_{DH} (time from OE to RAS), t_{OLZ} (time from OE to RAS), t_{OEZ} (time from OE to RAS).

The diagram also shows the Hi-Z (High Impedance) state for the L I/O signals during certain periods.

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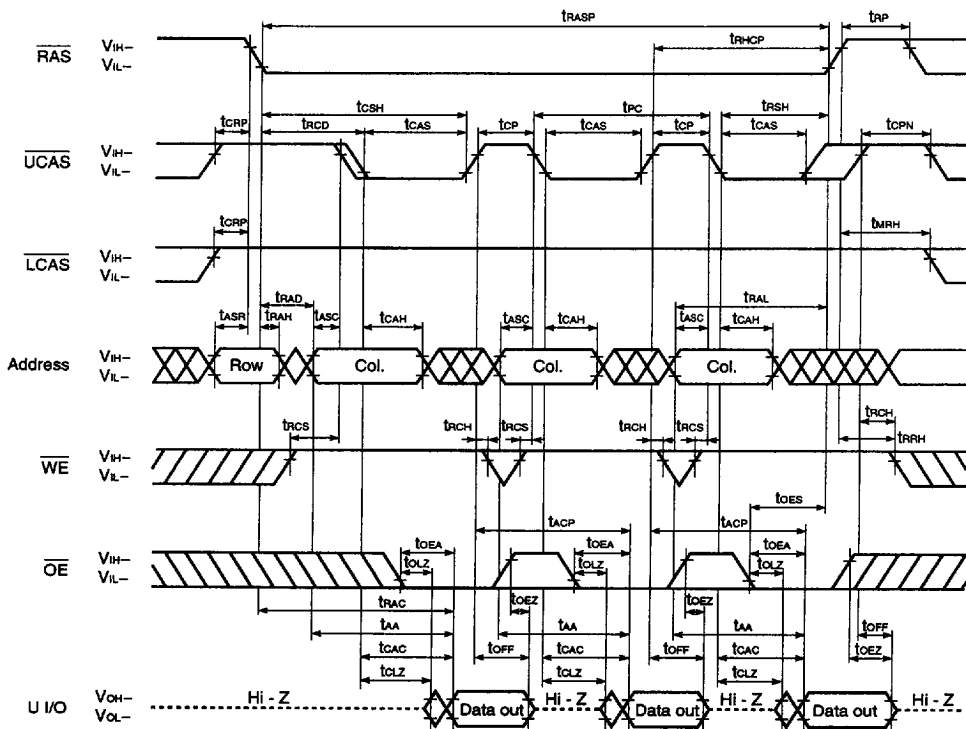
6427525 0057431 477

Fast Page Mode Read Cycle



Remark In the fast page mode, read, write and read modify write cycles are available for each of the consecutive $\overline{\text{CAS}}$ cycles within the same $\overline{\text{RAS}}$ cycle.

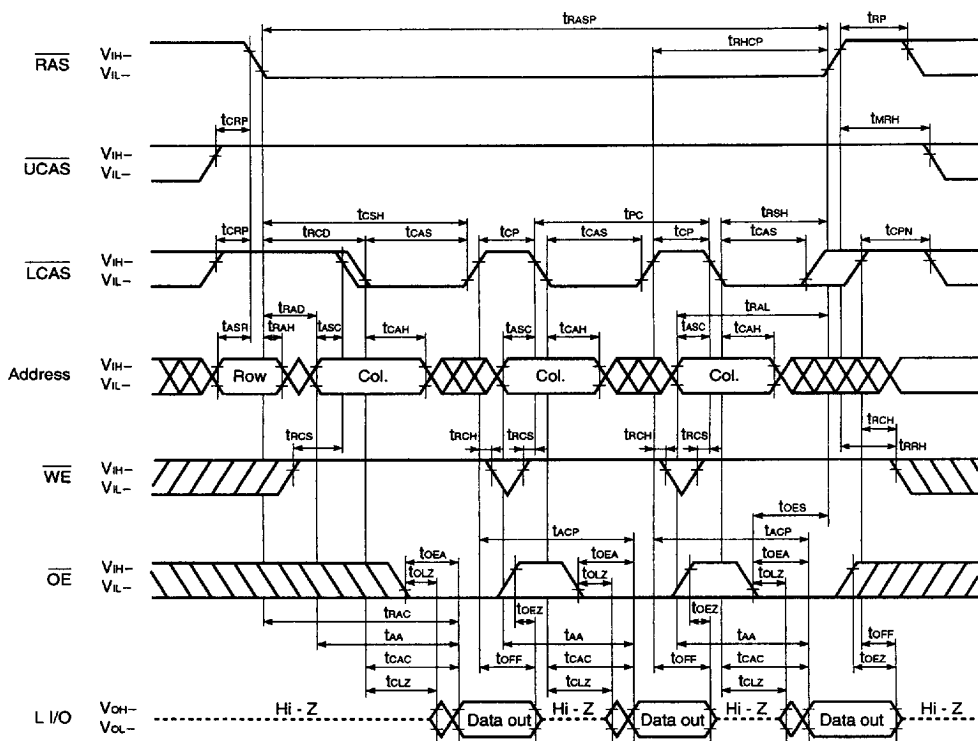
Fast Page Mode Upper Byte Read Cycle



Remark L I/O : Hi-Z

In the fast page mode, read, write and read modify write cycles are available for each of the consecutive $\overline{\text{CAS}}$ cycles within the same $\overline{\text{RAS}}$ cycle.

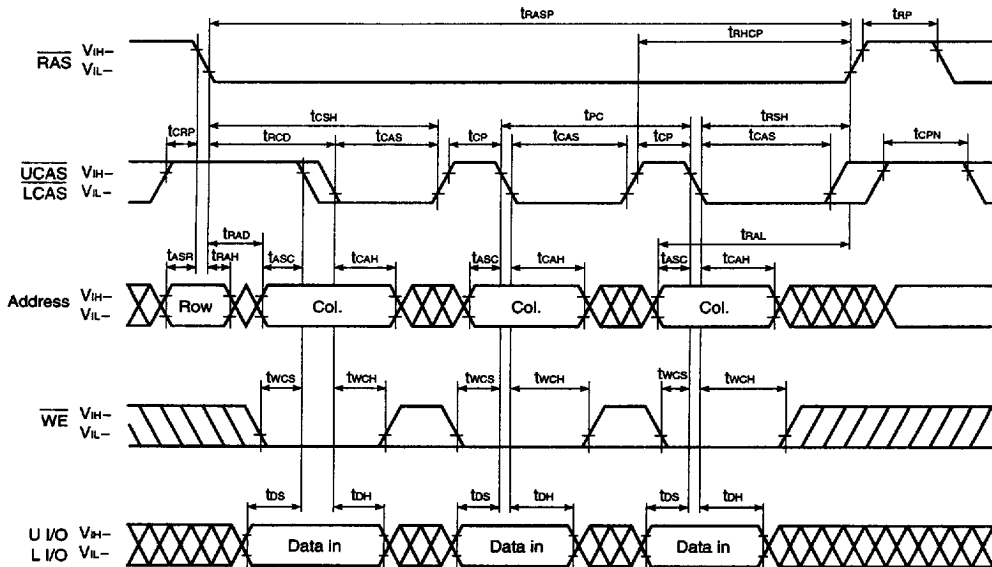
Fast Page Mode Lower Byte Read Cycle



Remark U I/O : Hi-Z

In the fast page mode, read, write and read modify write cycles are available for each of the consecutive $\overline{\text{CAS}}$ cycles within the same $\overline{\text{RAS}}$ cycle.

Fast Page Mode Early Write Cycle



Remark $\overline{\text{OE}}$: Don't care

In the fast page mode, read, write and read modify write cycles are available for each of the consecutive CAS cycles within the same RAS cycle.

The timing diagram illustrates the sequence of signals for the 64K1602 LCD module. The signals and their timing parameters are as follows:

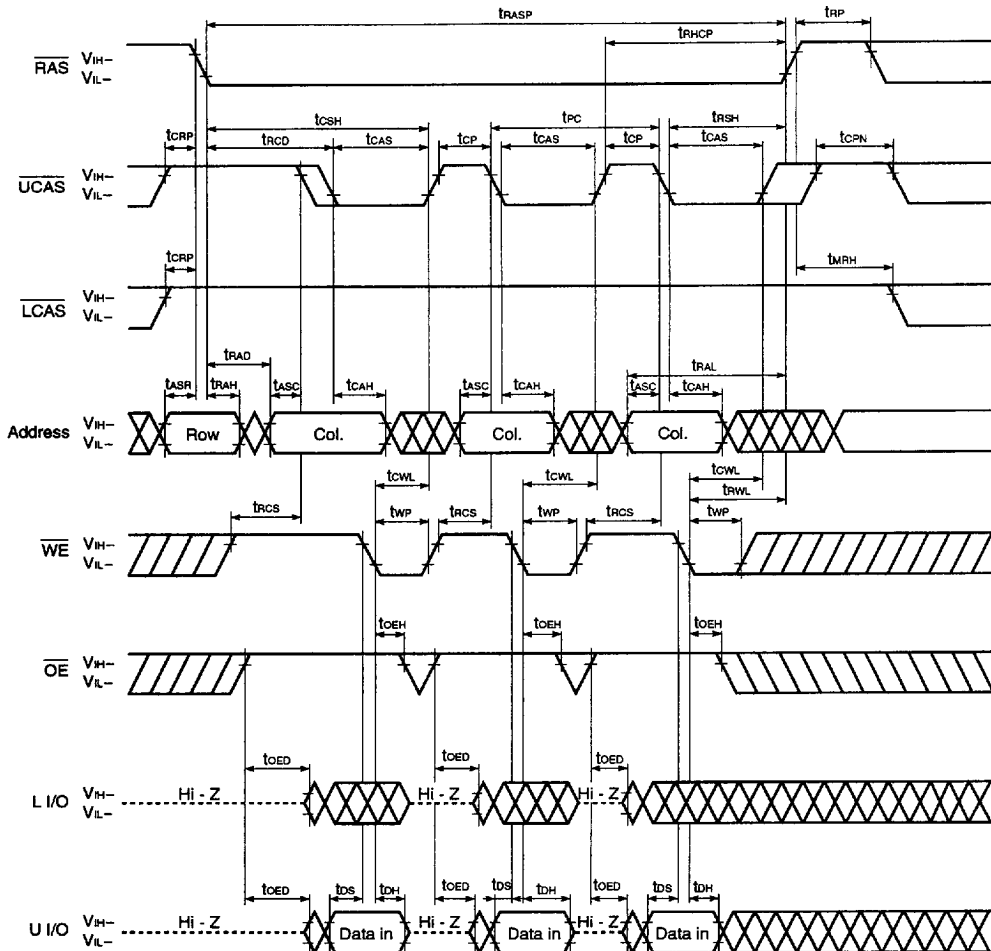
- RAS:** Row Address Strobe. Timing parameters include t_{RASP} (pulse width), t_{RHCP} (hold time), and t_{RP} (period).
- UCAS:** Column Address Strobe. Timing parameters include t_{CSP} (pulse width), t_{RCD} (setup time), t_{CSH} (hold time), t_{CAS} (access time), t_{CP} (period), t_{CRSH} (setup time), t_{CAS} (access time), t_{CPN} (period), and t_{MRH} (hold time).
- LCAS:** Line Address Strobe. Timing parameters include t_{CRP} (pulse width) and t_{MRH} (hold time).
- Address:** Shows Row and Column address periods. Timing parameters include t_{ASR} (setup time), t_{RAH} (hold time), t_{ASC} (access time), t_{CAH} (hold time), t_{ASC} (access time), t_{CAH} (hold time), t_{ASC} (access time), t_{CAH} (hold time), and t_{RAL} (hold time).
- WE:** Write Enable. Timing parameters include t_{WCS} (setup time) and t_{WCH} (hold time).
- U/I/O:** Data bus. Timing parameters include t_{DS} (setup time) and t_{DH} (hold time).

In the fast page mode, read, write and read modify write cycles are available for each of the consecutive $\overline{\text{CAS}}$ cycles within the same $\overline{\text{RAS}}$ cycle.

[illegible]

In the fast page mode, read, write and read modify write cycles are available for each of the consecutive $\overline{\text{CAS}}$ cycles within the same $\overline{\text{RAS}}$ cycle.

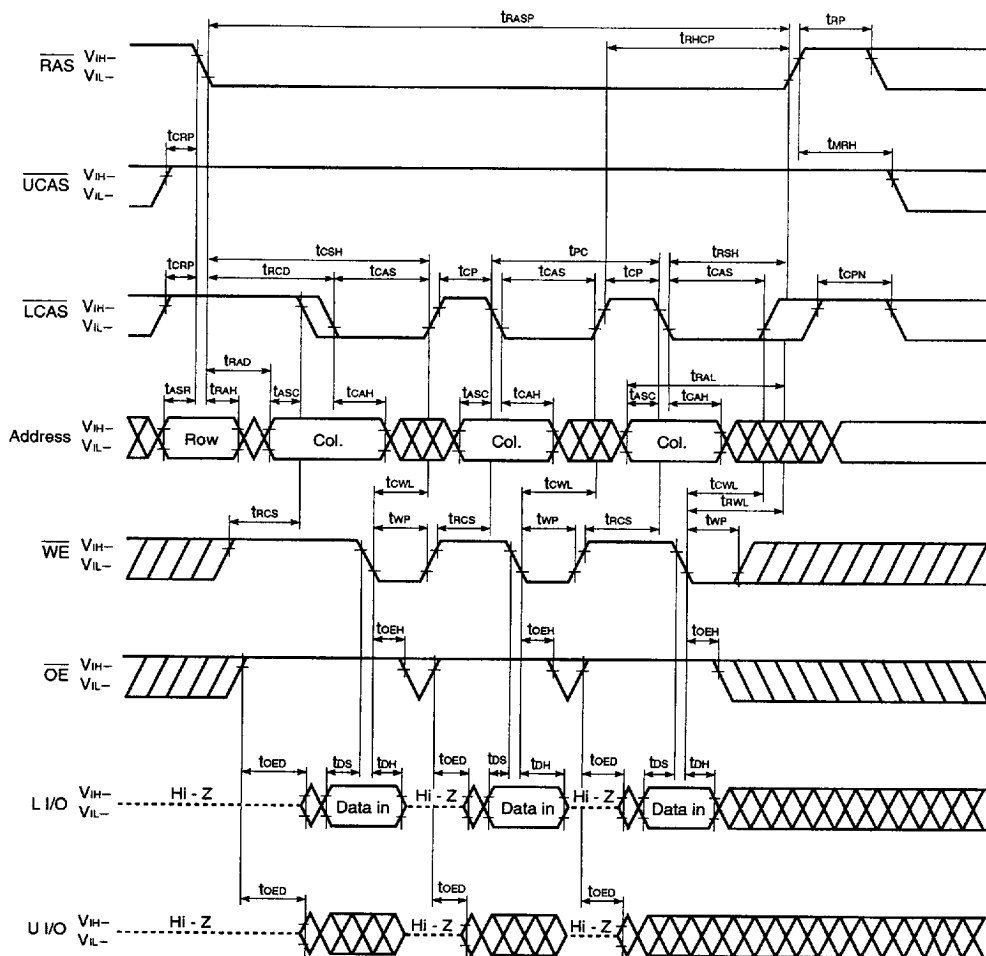
Fast Page Mode Upper Byte Late Write Cycle



Remark In this cycle, the input data to Lower I/O is ineffective.

In the fast page mode, read, write and read modify write cycles are available for each of the consecutive $\overline{\text{CAS}}$ cycles within the same $\overline{\text{RAS}}$ cycle.

Fast Page Mode Lower Byte Late Write Cycle



Remark In this cycle, the input data to Upper I/O is ineffective.

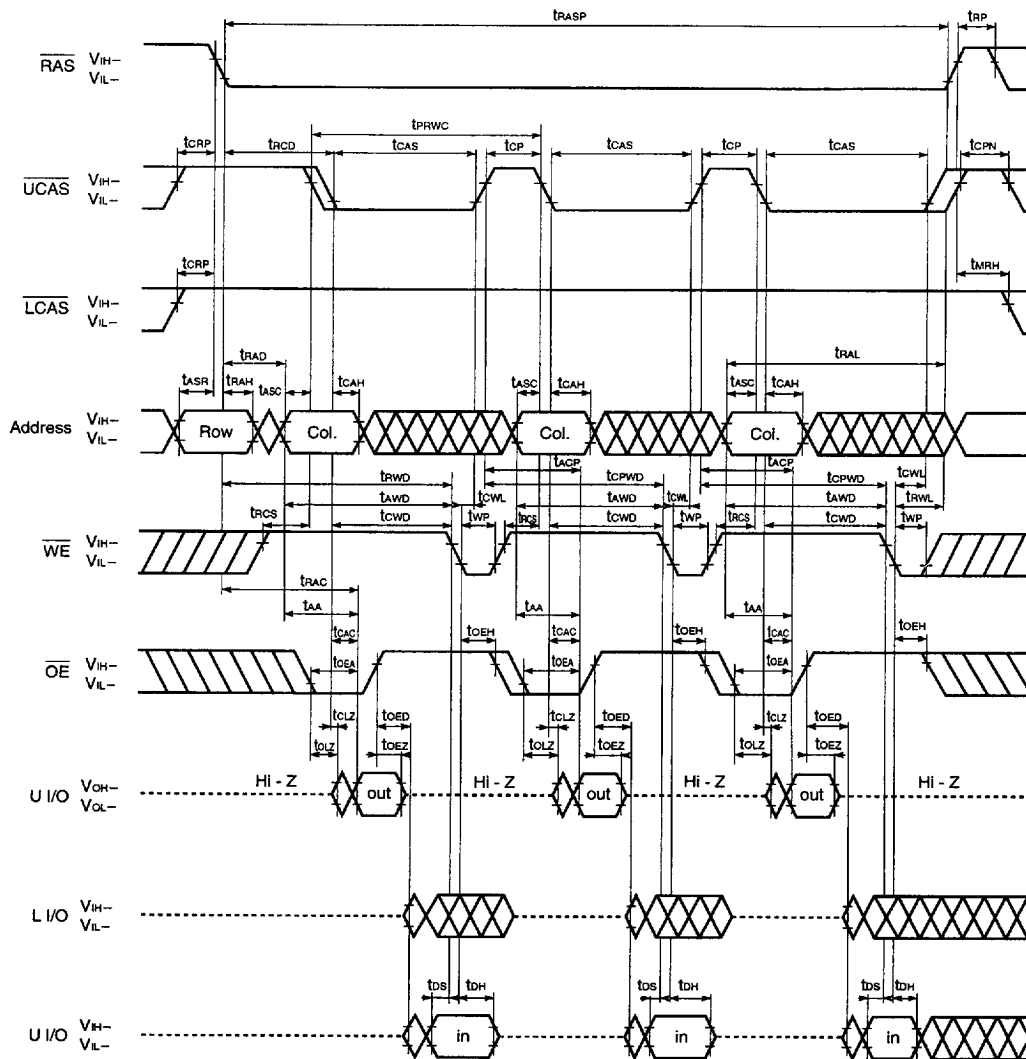
In the fast page mode, read, write and read modify write cycles are available for each of the consecutive $\overline{\text{CAS}}$ cycles within the same $\overline{\text{RAS}}$ cycle.

[illegible]

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Fast Page Mode Upper Byte Read Modify Write Cycle

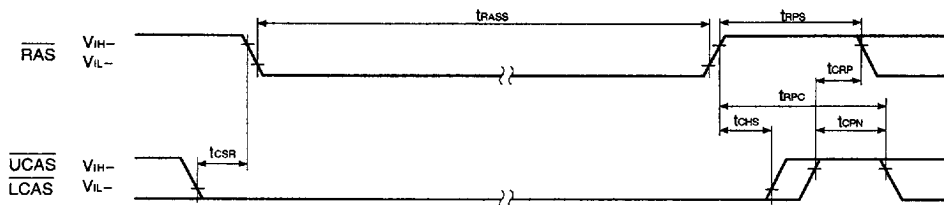


Remark In this cycle, the input data to Lower I/O is ineffective. The data out of that remains Hi-Z. In the fast page mode, read, write and read modify write cycles are available for each of the consecutive $\overline{\text{CAS}}$ cycles within the same $\overline{\text{RAS}}$ cycle.

[illegible]

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CAS Before RAS Self Refresh Cycle (Only for the μ PD42S16160L, 42S18160L)



Remark Address, $\overline{WE}$, $\overline{OE}$: Don't care L I/O, U I/O : Hi - Z

Cautions on Use of CAS Before RAS Self Refresh

CAS before RAS self refresh can be used independently when used in combination with distributed CAS before RAS long refresh; However, when used in combination with burst CAS before RAS long refresh or with burst long RAS only refresh, the following cautions must be observed.

(1) Normal Combined Use of CAS Before RAS Self Refresh and Burst CAS Before RAS Long Refresh

When CAS before RAS self refresh and burst CAS before RAS long refresh are used in combination, please perform CAS before RAS refresh as follows just before and after setting CAS before RAS self refresh.

μ PD42S16160L : 4 096 times within a 64 ms interval

μ PD42S18160L : 1 024 times within a 16 ms interval

(2) Normal Combined Use of CAS Before RAS Self Refresh and Burst Long RAS Only Refresh

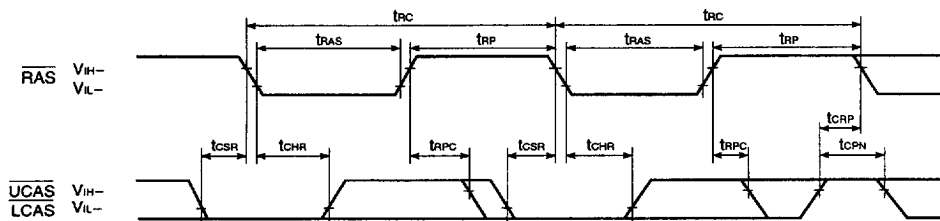
When CAS before RAS self refresh and burst RAS only refresh are used in combination, please perform RAS only refresh as follows just before and after setting CAS before RAS self refresh.

μ PD42S16160L : 4 096 times within a 64 ms interval

μ PD42S18160L : 1 024 times within a 16 ms interval

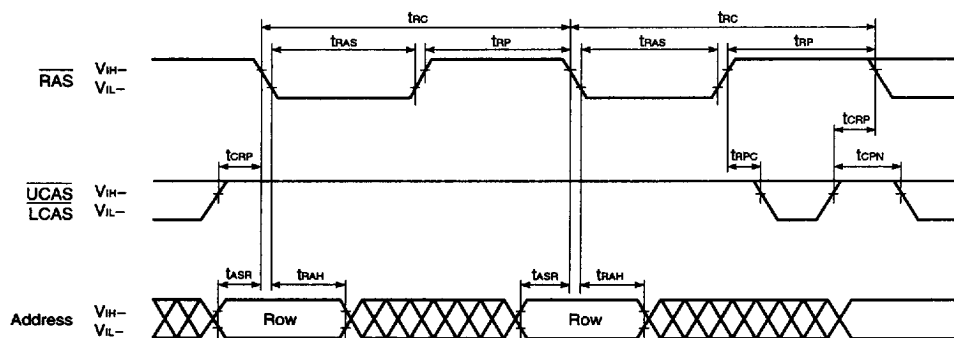
For details, please refer to **How to use DRAM User's Manual**.

CAS Before RAS Refresh Cycle



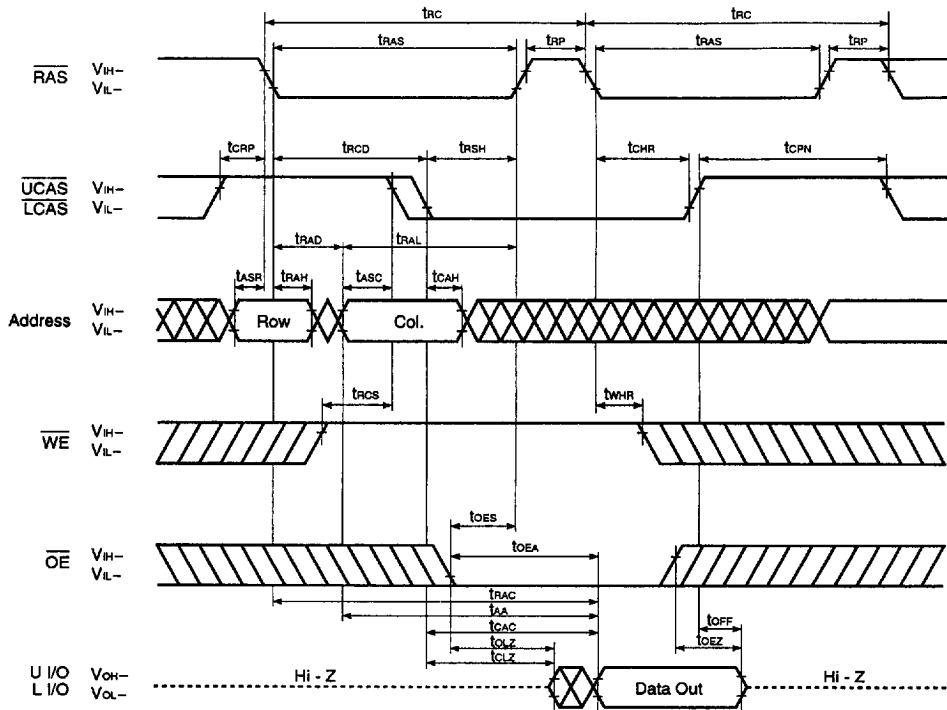
Remark Address, $\overline{WE}$, $\overline{OE}$: Don't care L I/O, U I/O : Hi - Z

RAS Only Refresh Cycle

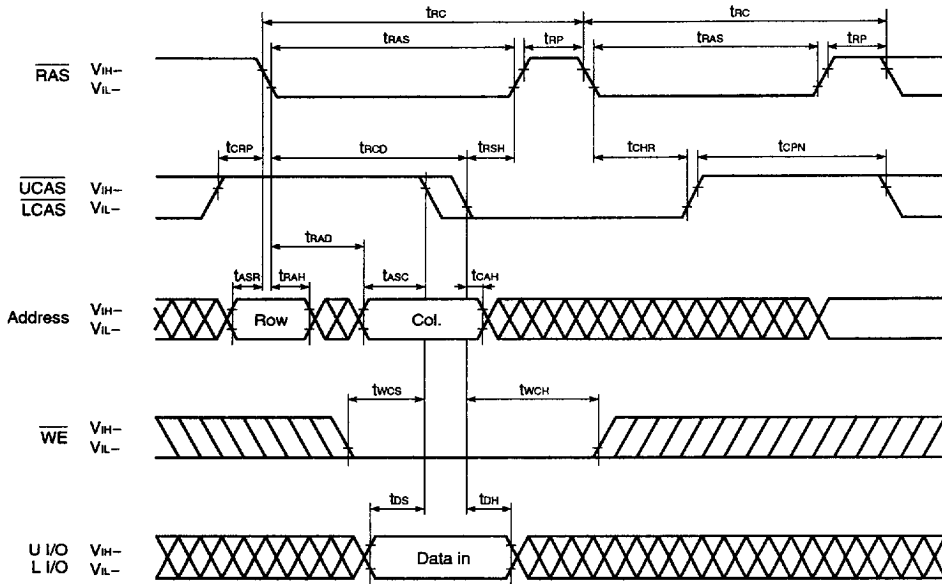


Remark $\overline{WE}$, $\overline{OE}$: Don't care L I/O, U I/O : Hi - Z

Hidden Refresh Cycle (Read)



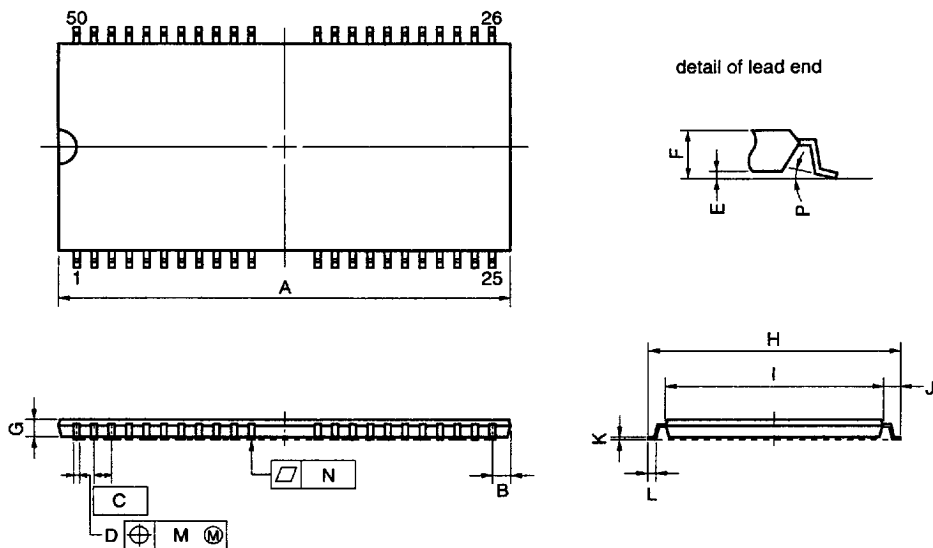
Hidden Refresh Cycle (Write)



Remark $\overline{\text{OE}}$: Don't care

Package Drawings

50 PIN PLASTIC TSOP (II) (400 mil)



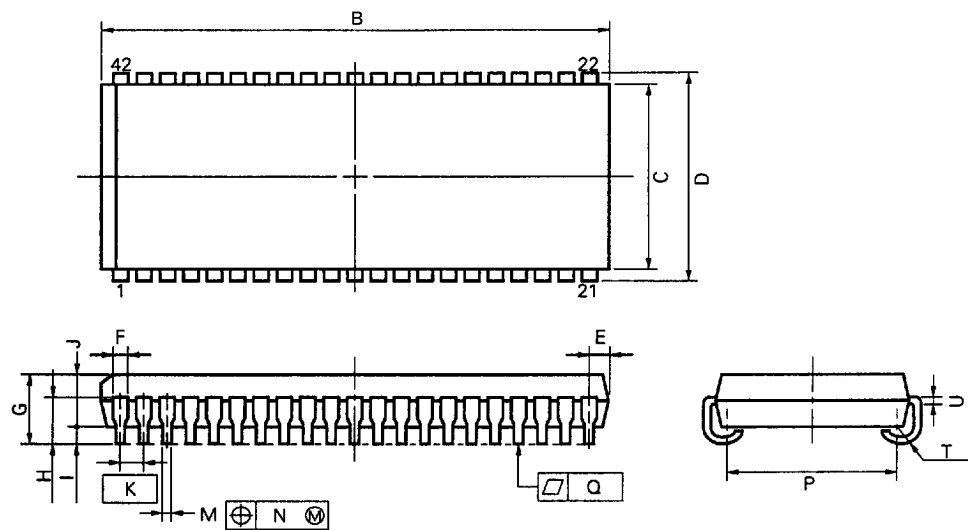
NOTE

Each lead centerline is located within 0.13 mm (0.005 inch) of its true position (T.P.) at maximum material condition.

ITEM	MILLIMETERS	INCHES
A	21.17 MAX.	0.834 MAX.
B	1.0 MAX.	0.040 MAX.
C	0.8 (T.P.)	0.031 (T.P.)
D	0.32 ^{+0.08} _{-0.07}	0.013±0.003
E	0.1±0.05	0.004±0.002
F	1.2 MAX.	0.048 MAX.
G	0.97	0.038
H	11.76±0.2	0.463±0.008
I	10.16±0.1	0.400±0.004
J	0.8±0.2	0.031 ^{+0.009} _{-0.008}
K	0.145 ^{+0.025} _{-0.015}	0.006±0.001
L	0.5±0.1	0.020 ^{+0.004} _{-0.005}
M	0.13	0.005
N	0.10	0.004
P	3° ^{+7°} _{-3°}	3° ^{+7°} _{-3°}

S50G5-80-7JF4

42 PIN PLASTIC SOJ (400 mil)



NOTE

Each lead centerline is located within 0.12 mm (0.005 inch) of its true position (T.P.) at maximum material condition.

P42LE-400A

ITEM	MILLIMETERS	INCHES
B	27.56 ^{+0.2} _{-0.35}	1.085 ^{+0.008} _{-0.014}
C	10.16	0.400
D	11.18±0.2	0.440±0.008
E	1.08±0.15	0.043 ^{+0.006} _{-0.007}
F	0.74	0.029
G	3.5±0.2	0.138±0.008
H	2.545±0.2	0.100±0.008
I	0.8 MIN.	0.031 MIN.
J	2.6	0.102
K	1.27 (T.P.)	0.050 (T.P.)
M	0.40±0.10	0.016 ^{+0.004} _{-0.005}
N	0.12	0.005
P	9.4±0.20	0.370±0.008
Q	0.10	0.004
T	R 0.85	R 0.033
U	0.20 ^{+0.10} _{-0.05}	0.008 ^{+0.004} _{-0.002}

Recommended Soldering Conditions

The following conditions (see tables below and next page) must be met when soldering μPD42S16160L, 4216160L, 42S18160L, 4218160L.

For more details, refer to our document "SEMICONDUCTOR DEVICE MOUNTING TECHNOLOGY MANUAL" (IEI-1207).

Please consult with our sales offices in case other soldering process is used, or in case the soldering is done under different conditions.

Types of Surface Mount Device

μPD42S16160LG5, 4216160LG5, 42S18160LG5, 4218160LG5 : 50-pin plastic TSOP (II) (400 mil)

Soldering process	Soldering conditions	Symbol
Infrared ray reflow	Peak temperature of package surface : 235 °C or below, Reflow time : 30 seconds or below (210 °C or higher), Number of reflow processes : MAX. 2 Exposure limit ^{Note} : 7 days (10 hours pre-baking is required at 125 °C afterwards) [Remark] (1) Please start the second reflow process after the temperature, raised by the first reflow process, returns to normal. (2) Please avoid removing the residual flux with water after the first reflow process.	IR35-107-2
VPS	Peak temperature of package : 215 °C or below, Reflow time : 40 seconds or below (200 °C or higher), Number of reflow processes : MAX. 2 Exposure limit ^{Note} : 7 days (10 hours pre-baking is required at 125 °C afterwards) [Remark] (1) Please start the second reflow process after the temperature, raised by the first reflow process, returns to normal. (2) Please avoid removing the residual flux with water after the first reflow process.	VP15-107-2
Partial heating method	Terminal temperature : 300 °C or below, Time : 3 seconds or below (Per one side of the device).	_____

Note Exposure limit before soldering after dry-pack package is opened.

Storage conditions: 25 °C and relative humidity at 65 % or less.

Caution Do not apply more than one soldering method at any one time, except for "Partial heating method".

μPD42S16160LLE, 4216160LLE, 42S18160LLE, 4218160LLE : 42-pin plastic SOJ (400 mil)

Soldering process	Soldering conditions	Symbol
Infrared ray reflow	Peak temperature of package surface : 235 °C or below, Reflow time : 30 seconds or below (210 °C or higher), Number of reflow processes : MAX. 2 Exposure limit ^{Note} : 7 days (20 hours pre-baking is required at 125 °C afterwards) [Remark] (1) Please start the second reflow process after the temperature, raised by the first reflow process, returns to normal. (2) Please avoid removing the residual flux with water after the first reflow process.	IR35-207-2
VPS	Peak temperature of package : 215 °C or below, Reflow time : 40 seconds or below (200 °C or higher), Number of reflow processes : MAX. 2 Exposure limit ^{Note} : 7 days (20 hours pre-baking is required at 125 °C afterwards) [Remark] (1) Please start the second reflow process after the temperature, raised by the first reflow process, returns to normal. (2) Please avoid removing the residual flux with water after the first reflow process.	VP15-207-2
Partial heating method	Terminal temperature : 300 °C or below, Time : 3 seconds or below (Per one side of the device).	_____

Note Exposure limit before soldering after dry-pack package is opened.

Storage conditions: 25 °C and relative humidity at 65 % or less.

Caution Do not apply more than one soldering method at any one time, except for "Partial heating method".